

CHIP CARRIER FOR A HIGH-FREQUENCY ELECTRONIC PACKAGE

ABSTRACT OF THE DISCLOSURE

5 An electronic package is provided. The electronic package includes a chip carrier having a first conductive layer which includes at least one signal track and at least one contact area, the contact area being electrically connected to the signal track and adapted for transmitting a high-frequency signal. The chip carrier further includes a reference structure having at least two conductive layers such that the signal track is electrically shielded by the reference structure. A semiconductor chip is positioned on the chip carrier and includes at least one terminal electrically interconnected to the at least one contact area.

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